

applying a first layer of titanium;

applying a second layer of copper on the first layer; and

applying a third layer of chrome on the second layer.

25. (Amended) The method according to claim 23, wherein the step of applying the dielectric into the recess comprises:

applying a dry etch bisbenzocyclobutene dielectric;

removing the dry etch bisbenzocyclobutene dielectric from the top terminal and a part of the conductive layer;

applying a photo definable bisbenzocyclobutene dielectric; and

exposing the top terminal and the part of the conductive layer.

39. (Amended) The method according to claim 38, wherein the step of applying the layer of electrically conductive material comprises:

applying a first layer of titanium;

applying a second layer of copper on the first layer; and

applying a third layer of chrome on the second layer.

REMARKS

In the office action dated August 8, 2001, the Examiner restricted the claims of the above application into two groups. Group I includes "device" claims 1-22, 24-25, 23-26, and 39 while Group II includes method claims 23, 26-31, and 37-38. Applicant elects claims 1-22 and 23-36 in Group I without traverse.